



Material Content Data Sheet



Sales Product Name				BSC094N06LS5		Issued		2. August 2019	
MA#				MA005345860					
Package				PG-TDSON-8-51		Weight*		101.38 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.281	0.28	0.28	2774	2774	
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		134		
	non noble metal	zinc	7440-66-6	0.055	0.05		538		
	non noble metal	iron	7439-89-6	1.090	1.08		10755		
wire	non noble metal	copper	7440-50-8	44.271	43.67	44.81	436685	448112	
	noble metal	gold	7440-57-5	0.028	0.03	0.03	280	280	
	encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		876	
plastics	plastics	epoxy resin	-	4.085	4.03		40290		
	inorganic material	silicondioxide	60676-86-0	40.224	39.68	43.80	396766	437932	
	leadfinish	non noble metal	tin	7440-31-5	1.264	1.25	1.25	12465	12465
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	286	286	
solder	noble metal	silver	7440-22-4	0.011	0.01		113		
	non noble metal	tin	7440-31-5	0.023	0.02		226		
	non noble metal	lead	7439-92-1	0.424	0.42	0.45	4184	4523	
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	zinc	7440-66-6	0.011	0.01		112		
	non noble metal	iron	7439-89-6	0.228	0.22		2247		
	non noble metal	copper	7440-50-8	9.250	9.12	9.35	91241	93628	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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